

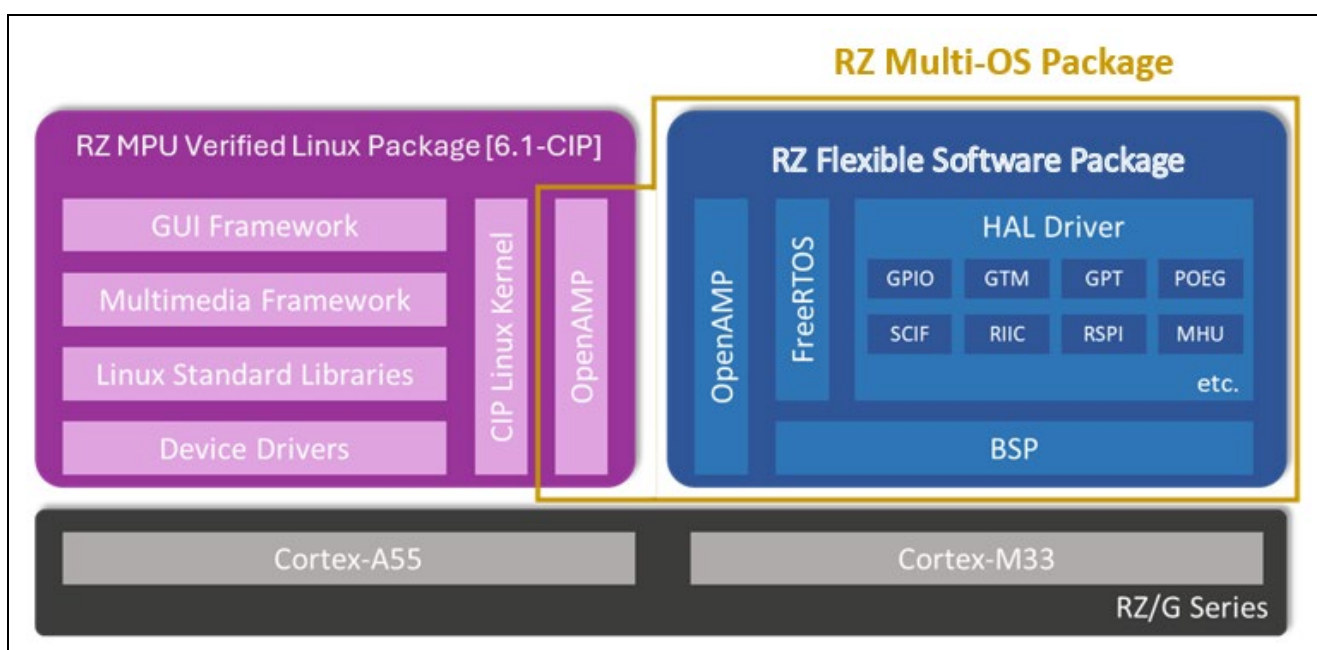
RZ/G2L, RZ/G2LC, RZ/G2UL

Quick Start Guide for RZ Multi-OS Package

Introduction

This document outlines the procedure for integrating the RZ Multi-OS Package into the RZ/G Verified Linux Package (referred to as VLP) for the RZ/G2L, RZ/G2LC and RZ/G2UL. By integrating the Multi-OS Package, users can efficiently establish a Multi-OS environment wherein Linux operates on the Cortex®-A55 and FreeRTOS/BareMetal runs on the Cortex-M33, with support for Inter-Processor Communication between these CPU cores.

This package requires the RZ Flexible Software Package (FSP) for an RTOS/BareMetal environment. The figure below illustrates the software stack for integrating the RZ Multi-OS Package with the RZ/G2L, RZ/G2LC and RZ/G2UL:



Here are brief descriptions of each component included in RZ Multi-OS Package:

- **RZ FSP**
This software package consists of production ready peripheral drivers, FreeRTOS and portable middleware stacks and best in-case HAL drivers with low memory footprint.
- **OpenAMP**
The framework includes the software components required for Asymmetric Multiprocessing (AMP) systems, such as Inter-Processor Communication.

Target Device

RZ/G2L
RZ/G2LC
RZ/G2UL

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1. Specifications

Table 1-1 lists the on-chip peripheral modules to be used in this package.

Table 1-1 Peripheral modules to be used in this package

Peripheral module	Usage
Message Handling Unit (MHU)	Configure Inter-Processor Interrupt.
Serial Communications Interface with FIFO (SCIFA)	Perform standard serial communications sending and receiving console messages.
Interrupt controller (INTC)	Handle the following types of interrupts as shown below for example: - Processors should receive interrupts during buffered serial communications. - MHU module fires Inter-Processor Interrupt.
General Purpose Input Output (GPIO)	Configure I/O lines used by serial communications.
General Timer (GTM)	Configure the tick for FreeRTOS.

2. Verified Operation Conditions

Table 2-1 shows the verified operation conditions.

Table 2-1 Verified Operation Conditions

Item	Contents
Integrated Development Environment	e ² studio 2026-07 or later
Toolchain	GNU Arm Toolchain 13.3.Rel1 AArch32 bare-metal target (arm-none-eabi)
Dependent Software	- RZ Flexible Software Package (FSP) v4.2.0 - RZ/G Verified Linux Package v3.0.7-update5 - RZ MPU Verified Linux Package v4.0.1

3. Sample Program Setup

3.1 Flexible Software Package Setup

Multi-OS Package expects RZ Flexible Software Package (FSP) to be installed in advance. For details on the installation, please refer to [Getting Started with Flexible Software Package](#).

3.2 Integration of OpenAMP related stuff

3.2.1 Using RZ MPU VLP v4.0.1

This section describes how to integrate OpenAMP related stuff to RZ MPU Verified Linux Package [6.1-CIP] (hereinafter referred to as VLP). The steps are based on **RZ/G2L and RZ/G2LC-EVKIT Linux Start-up Guide** (hereinafter referred to as **Linux Start-up Guide**) included in **RZ MPU VLP v4.0.1**.

- Follow the procedure stated from the beginning of **2.2 Building Images** to **(4) Add layers of Linux Start-up Guide**.
- Download Multi-OS Package (r01an8260ej0420-rz-multi-os-pkg.zip) to a working directory and run the RZ MPU VLP v4.0.1

```
$ cd ~/rz_vlp_<pkg ver>
$ unzip <Multi-OS Dir>/r01an8260ej0420-rz-multi-os-pkg.zip
$ tar zxvf r01an8260ej0420-rz-multi-os-pkg/meta-rz-features_multi-os_v4.2.0.tar.gz
```

Here, <pkg_ver> and <Multi-OS Dir> indicate the version number of VLP (e.g. v4.0.1) and the path to the directory where Multi-OS Package is placed respectively.

3. Add the layer for Multi-OS Package, simply run the helper script and select the **meta-rzg2l-vlp4** layer from the list.

```
$ cd build
$ bash ../meta-rz-features/meta-rz-multi-os/add_meta_layer.sh
```

(Optional for remoteproc support)

4. Uncomment the following lines stated in **meta-rz-features/meta-rz-multi-os/meta-rzg/meta-rzg2l/meta-rzg2l-vlp4/conf/layer.conf** for enabling remoteproc support:

```
MACHINE_FEATURES:append = " RZ_REMOTEPROC"
```

5. Start a build as described in **(6) Start a build of 2.2 Building Images** as shown below:

```
$ MACHINE=<board> bitbake core-mage-<target>
```

For details on the allowable value of <board> and <target>, please refer to **Linux Start-up Guide**.

3.2.2 Using RZ/G VLP v3.0.7

This section describes how to integrate OpenAMP related stuff to RZ/G Verified Linux Package [5.1-CIP] (hereinafter referred to as VLP). The steps are based on **RZ/G2L, RZ/G2LC and RZ/G2UL-EVKIT Linux Start-up Guide** (hereinafter referred to as **Linux Start-up Guide**) included in **RZ/G VLP v3.0.7**.

1. Follow the procedure stated from the beginning of **2.2 Building Images** to **(4) Add layers of Linux Start-up Guide**.
2. Download Multi-OS Package (r01an8260ej0420-rz-multi-os-pkg.zip) to a working directory and run the commands stated below:

```
$ cd ~/rzg_vlp_<pkg_ver>
$ unzip <Multi-OS Dir>/r01an8260ej0420-rz-multi-os-pkg.zip
$ tar zxvf r01an8260ej0420-rz-multi-os-pkg/meta-rz-features_multi-os_v4.2.0.tar.gz
```

Here, <pkg_ver> and <Multi-OS Dir> indicate the version number of VLP (e.g. v3.0.7) and the path to the directory where Multi-OS Package is placed respectively.

3. Add the layer for Multi-OS Package, simply run the helper script and select the **meta-rzg2l-vlp3** layer from the list.

```
$ cd build
$ bash ../meta-rz-features/meta-rz-multi-os/add_meta_layer.sh
```

(Optional for remoteproc support)

4. Uncomment the following lines stated in **meta-rz-features/meta-rz-multi-os/meta-rzg/meta-rzg2l/meta-rzg2l-vlp3/conf/layer.conf** for enabling remoteproc support:

```
MACHINE_FEATURES_append = " RZ_REMOTEPROC"
```

5. Note: If any Patch files at '5. Notes' in **RZ/G Verified Linux Package Version 3.0.7-update5 Release Note** - Rev. 1.20 (hereinafter referred to as VLP3.0.7-update5 Release Note) are applied, please follow the below notes:
Note 5.1: if the **(4) To update u-boot** part in '5. Notes' is applied, please ignore the instructions in this part, and follow the instructions as below:

```
$ TEMPLATECONF=$PWD/meta-renesas/meta-rzg2l/docs/template/conf/ \
source poky/oe-init-build-env build
```

```
$ MACHINE=smarc-rzg2l bitbake u-boot -c devshell
# Apply {patch_name} at
# tmp/work/smarc_rzg2l-poky-linux/u-boot/1_v2021.10+gitAUTOINC+57c087bafa-r0/git
$ git apply ~/rzg_vlp_${PACKAGE_VERSION}/extra/u-boot/{patch_name}
$ exit
$ MACHINE=smarc-rzg2l bitbake u-boot -C compile
```

Note 5.2: please make sure that the layer for Multi-OS Package is added before applying the Patch files at '5. Notes' in **VLP3.0.7-update5 Release Note**.

6. Start a build as described in **(6) Start a build of 2.2 Building Images** as shown below:

```
$ MACHINE=<board> bitbake core-image-<target>
```

For details on the allowable value of <board> and <target>, please refer to **Linux Start-up Guide**.

3.3 Note for integration

By default, all clock-related configuration is handled on the Linux (main core) side. If the system design is changed such that clocks for specific drivers are configured by the RTOS (sub core) side, the implementation must be customized to ensure these settings do not conflict with Linux's clock initialization sequence.

The peripherals which are NOT enabled enter Module Standby Mode after Linux kernel is booted up. That means the peripherals used on sub core (CM33) might stop working at that time. To avoid such a situation, Multi-OS Package incorporates the patch below:

3.3.1 For RZ/G2L, RZ/G2LC

- 0006-clk-renesas-r9a07g044-Set-SCIF1-SCIF2-OSTM2.patch

This patch prevents SCIF channel1, SCIF channel 2 and GTM channel 2 used in RPMsg example program from entering Module Standby Mode. If you have any other peripherals which you would like to stop entering Module Standby implicitly, please apply the patch as shown below:

```
drivers/clock/renesas/r9a07g044-cpg.c | 3 +++
1 file changed, 3 insertions(+)

diff --git a/drivers/clock/renesas/r9a07g044-cpg.c
b/drivers/clock/renesas/r9a07g044-cpg.c
index e27caa075af7a..f3cda2e05757f 100644
--- a/drivers/clock/renesas/r9a07g044-cpg.c
+++ b/drivers/clock/renesas/r9a07g044-cpg.c
@@ -449,6 +449,9 @@ static const unsigned int r9a07g044_crit_mod_clks[]
__initconst = {
    MOD_CLK_BASE + R9A07G044_IA55_PCLK,
    MOD_CLK_BASE + R9A07G044_IA55_CLK,
    MOD_CLK_BASE + R9A07G044_DMACE_CLK,
+   MOD_CLK_BASE + R9A07G044_SCIF2_CLK_PCK,
+   MOD_CLK_BASE + R9A07G044_OSTM2_PCLK,
+   MOD_CLK_BASE + R9A07G044_SCIF1_CLK_PCK,
+   MOD_CLK_BASE + R9A07G044_XXXX,
};
```

With respect to the allowable value for **XXXX**, please refer to the link below:

- https://github.com/renesas-rz/rz_linux-cip/blob/f12a03d8f2cf971734190c35aeaac98dde815b2d/drivers/clk/renesas/r9a07g044-cpg.c#L244-L412

3.3.2 For RZ/G2UL

- 0008-clk-renesas-r9a07g043-Set-OSTM2.patch

This patch prevents GTM channel 2 used in RPMsg example program from entering Module Standby Mode. If you have any other peripherals which you would like to stop entering Module Standby implicitly, please apply the patch as shown below:

```
drivers/clk/renesas/r9a07g043-cpg.c | 1 +
1 file changed, 1 insertion(+)

diff --git a/drivers/clk/renesas/r9a07g043-cpg.c
b/drivers/clk/renesas/r9a07g043-cpg.c
index dad498e1b0693..296923ad08f1f 100644
--- a/drivers/clk/renesas/r9a07g043-cpg.c
+++ b/drivers/clk/renesas/r9a07g043-cpg.c
@@ -399,6 +399,7 @@ static const unsigned int r9a07g043_crit_mod_clks[]
__initconst = {
    MOD_CLK_BASE + R9A07G043_IA55_PCLK,
    MOD_CLK_BASE + R9A07G043_IA55_CLK,
    MOD_CLK_BASE + R9A07G043_DMACH_ACLK,
+   MOD_CLK_BASE + R9A07G043_OSTM2_PCLK,
+   MOD_CLK_BASE + R9A07G043_XXXX,
};
```

With respect to the allowable value for **XXXX**, please refer to the link below:

- https://github.com/renesas-rz/rz_linux-cip/blob/f12a03d8f2cf971734190c35aeaac98dde815b2d/drivers/clk/renesas/r9a07g043-cpg.c#L165-L308

3.4 Deployment of RZ/G VLP

With respect to the deployment of Linux kernel, device tree and root filesystem for RZ/G2L, RZ/G2LC and RZ/G2UL, please refer to **Linux Start-up Guide**.

4. Sample Program Invocation on RZ/G2L SMARC EVK

4.1 Hardware Setup

1. Connect SEGGER J-Link to RZ/G2L SMARC EVK. For details, please refer to [Getting Started with Flexible Software Package](#).
2. Connect [Pmod USBUART](#) to the upper side of Pmod 1 of SMARC Carrier Board as shown below for securing the console for the program running on CM33.

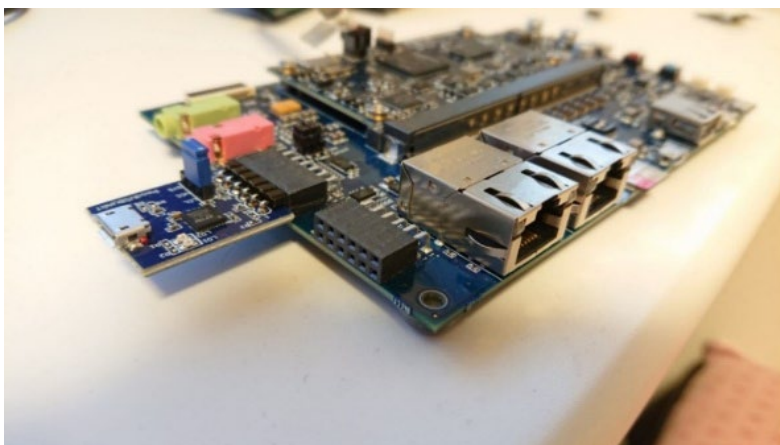


Figure 4-1. Connection between RZ/G2L SMARC EVK and Pmod USBUART

Note: There is no valid SCIF channel connected to Pmod 0 or Pmod 1 on RZ/G2UL Smarc EVK

4.2 CM33 sample project Setup

This section describes how to set up CM33 sample project.

1. Extract **r01an8260ej0420-rz-multi-os-pkg.zip** on your development PC.
2. Extract **rzg2l_cm33_rpmsg_linux_rtos_example.zip** included in the unzipped r01an8260ej0420-rz-multi-os-pkg.zip.
3. Open e² studio 2026-07 and click **File > Import**.
4. Double-click **General** and select **Existing Projects into Workspace** as shown in Figure 4-2:

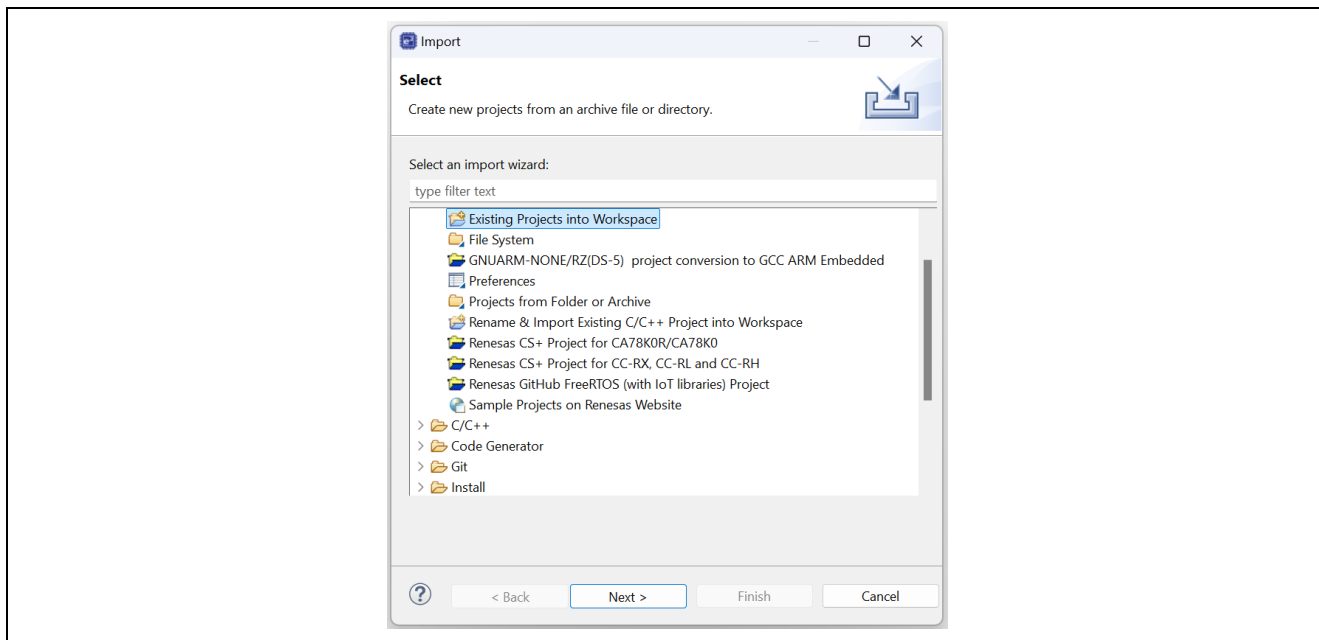


Figure 4-2. Import sample project (1)

5. Input the path to the directory **rzg2l_cm33_rpmsg_linux_rtos_example**, press **Enter** key and click **Finish** button.

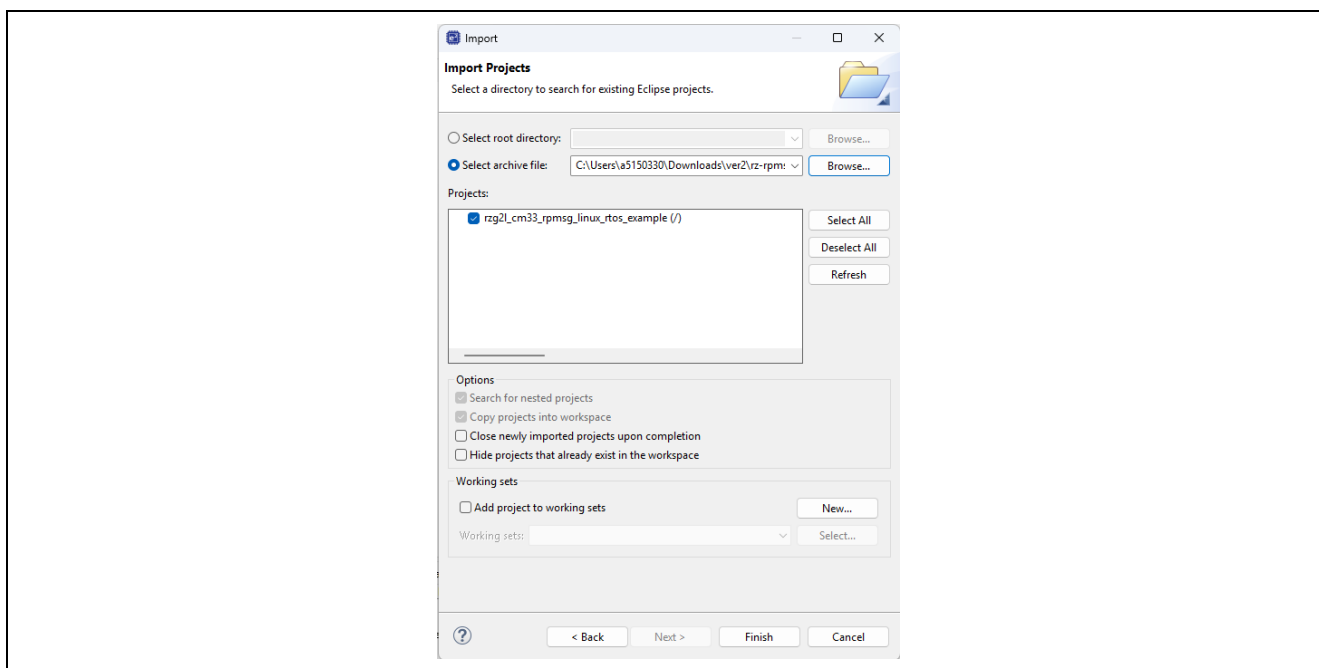


Figure 4-3. Import sample project (2)

(Optional for configuring RPMsg channel)

6. By default, RPMsg channel 0 is configured to be used on CM33. If you would like to use channel 1, please open the property of MainTask#0 on FSP Smart Configurator, specify 1 for Thread Context, and push **General Project Content** button. If **Generate Project Content** pop-up is shown, click **Proceed** to reflect the change to the source code.

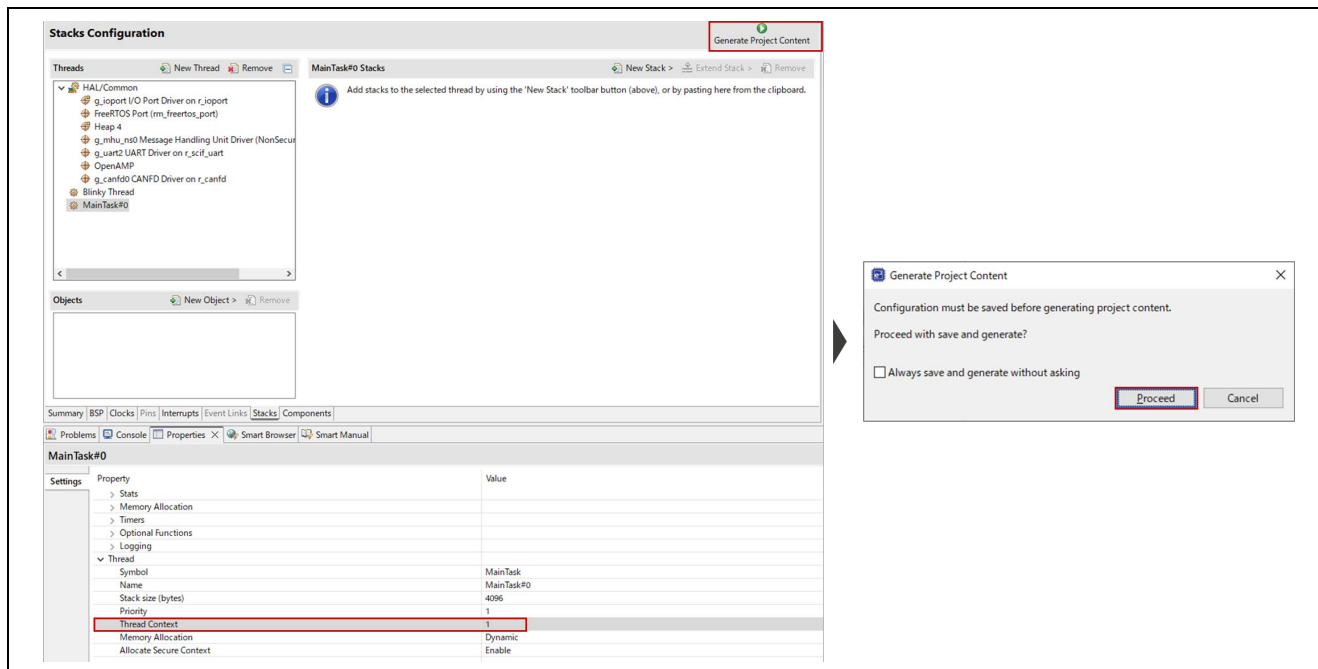


Figure 4-4. RPMsg Channel Setting

(Optional for remoteproc support)

7. Change the value for **ENABLE_REMOTEPROC** defined in **platform_info.h** from 0 to 1 as shown below:

```
#define ENABLE_REMOTEPROC (1U)
```

8. Build the project from **Choose Project > Build Project**.
9. The following files should be generated in **Debug** and/or **Release** directory in accordance with the active Build Configuration if there are no build failures.
- rzg2l_cm33_rpmsg_linux_rtos_example.elf
 - rzg2l_cm33_rpmsg_linux_rtos_example_non_secure_code.bin
 - rzg2l_cm33_rpmsg_linux_rtos_example_non_secure_vector.bin
 - rzg2l_cm33_rpmsg_linux_rtos_example_secure_code.bin
 - rzg2l_cm33_rpmsg_linux_rtos_example_secure_vector.bin

4.3 CM33 sample program invocation

4.3.1 CM33 sample program invocation with SEGGER J-Link

You need to follow the steps stated below to invoke CM33 sample program with SEGGER J-Link:

1. Click the debug button indicated by a red arrow as shown below:

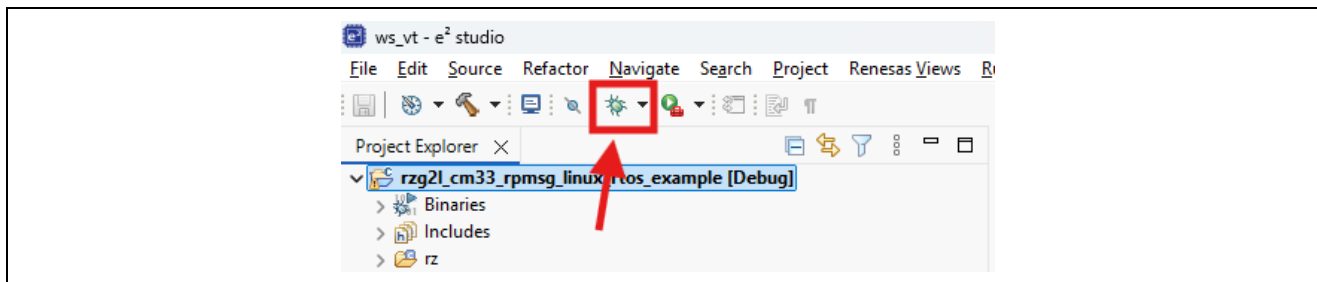


Figure 4-5. Selection of Debug Configuration

2. Choose **rzg2l_cm33_rpmsg_linux_rtos_example Debug_Flat** or **rzg2l_cm33_rpmsg_linux_rtos_example Release_Flat** from the drop-down list indicated in Figure 4-6.

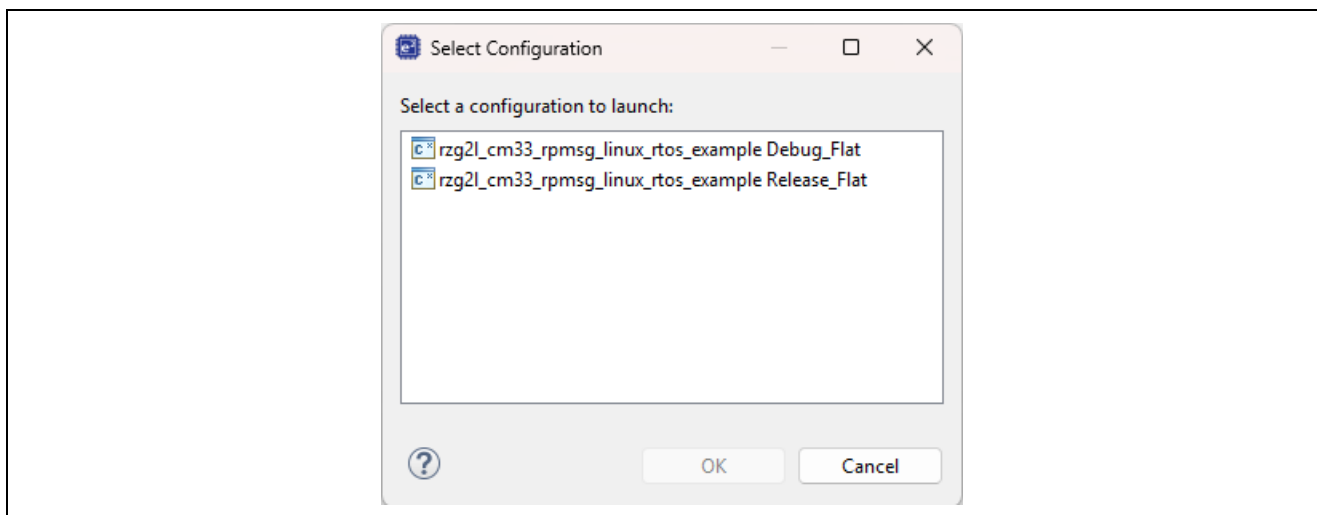


Figure 4-6. Debug Function Launch

If **Confirm Perspective Switch** window below appears, press **Switch** to go ahead.

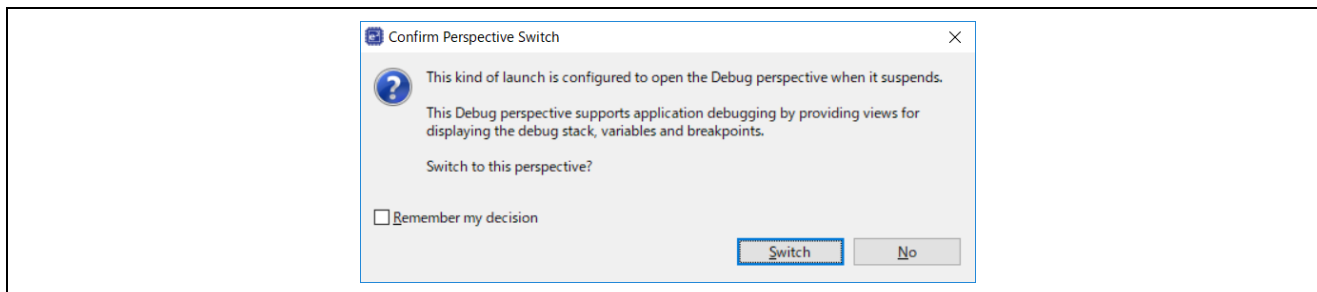


Figure 4-7. Confirm Perspective Switch window

3. When Debug Perspective is opened, Program Counter (PC) should be located at the top of Warm_Reset_S function. Then, you need to press the button indicated by a red arrow in Figure 4-8.

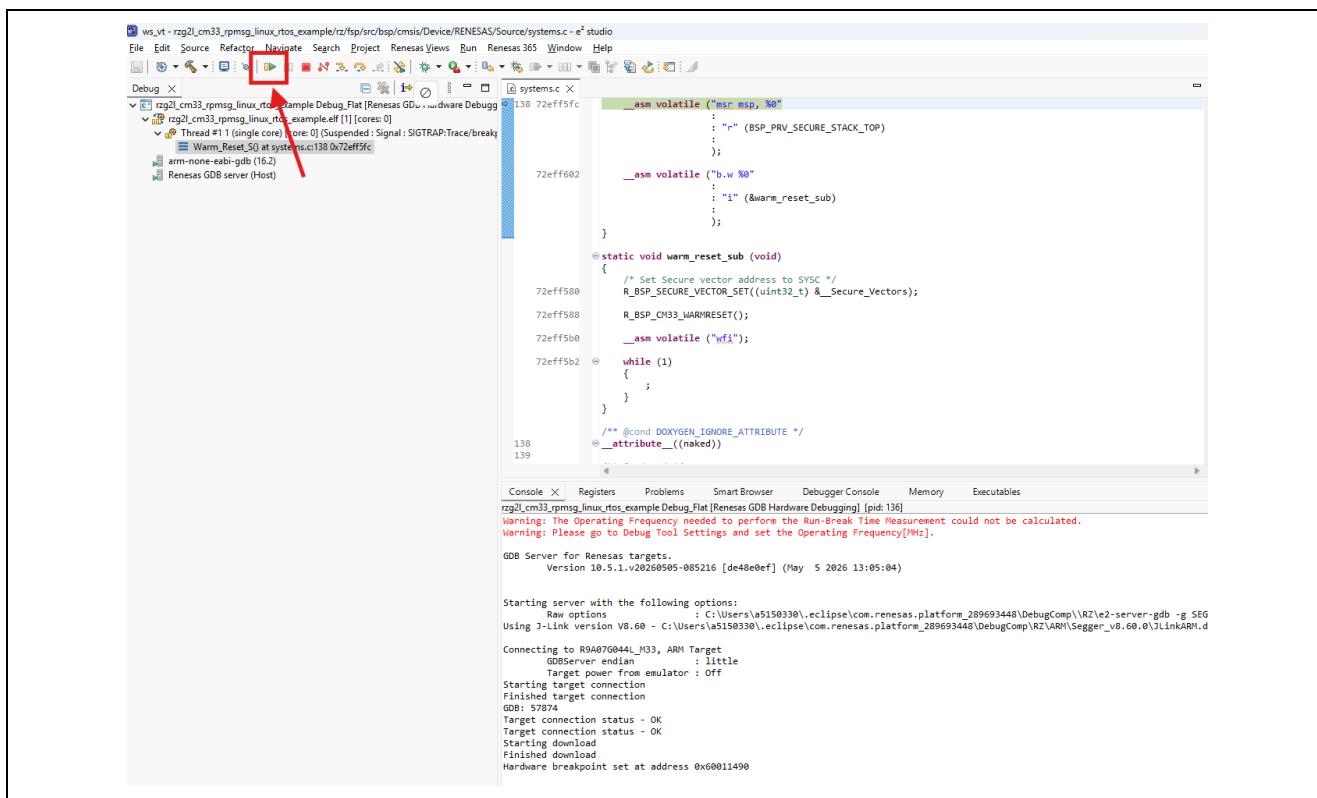


Figure 4-8. How to start to debug sample project (1)

4. Program stops at the top of main function. So, please click the same button as the previous step.

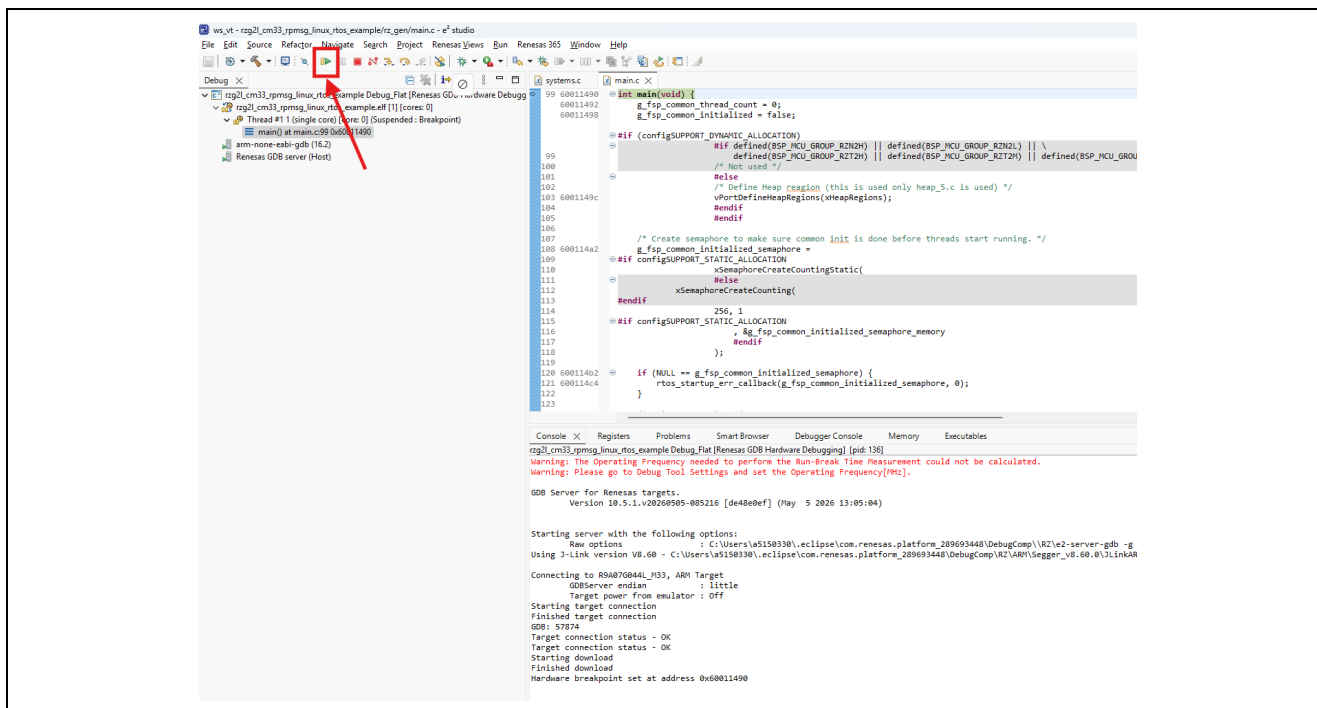


Figure 4-9. How to start to debug sample project (2)

5. Now that CM33 sample project has started, the following message is shown on the console associated with Pmod USBUART:

```
Successfully probed IPI device
Successfully open uio device: 42F00000.rsctbl.
Successfully added memory device 42F00000.rsctbl.
Successfully open uio device: 43000000.vring-ctl0.
Successfully added memory device 43000000.vring-ctl0.
Successfully open uio device: 43200000.vring-shm0.
Successfully added memory device 43200000.vring-shm0.
Initialize remoteproc successfully.
creating remoteproc virtio
initializing rpmsg vdev
```

Please note that CM33 sample program is waiting for the establishment of RPMsg channel between CM33 and CA55.

Note: There is no valid SCIF channel connected to Pmod 0 or Pmod 1 on RZ/G2UL SMARC EVK and so, any message won't be shown with RZ/G2UL.

4.3.2 CM33 sample program invocation with u-boot

You can invoke CM33 sample program from u-boot by following the procedure described below:

1. Copy the binary files generated at 8 of section 4.2 to microSD card.
2. Insert the microSD card into CN10 of SMARC Carrier Board.
3. Turn on SMARC EVK by pressing the Power button for a few seconds.
4. Hit any key to stop autoboot within 3 seconds after the following message is shown in the console connected to CN14 of SMARC Carrier Board:

```
U-Boot 2024.07 (Sep 22 2025 - 10:51:32 +0000)
```

```
CPU:   Renesas Electronics CPU rev 1.0
Model: smarc-rzg2l
DRAM:  1.9 GiB
WDT:   watchdog@0000000012800800
WDT:   Started with servicing (60s timeout)
MMC:   sd@11c00000: 0, sd@11c10000: 1
Loading Environment from MMC... OK
In:    serial@1004b800
Out:   serial@1004b800
Err:   serial@1004b800
U-boot WDT started!
Net:   eth0: ethernet@11c20000
Hit any key to stop autoboot: 2
=>
```

5. Load the binary files you copied at step1 from microSD card to RAM by executing the commands stated below on the console. Here, N stands for the partition number in which you stored the binary files.

```
dcache off
mmc dev 1
fatload mmc 1:N 0x0001FF80 rzg2l_cm33_rpmsg_linux_rtos_example_secure_vector.bin
fatload mmc 1:N 0x42EFF440 rzg2l_cm33_rpmsg_linux_rtos_example_secure_code.bin
fatload mmc 1:N 0x00010000
rzg2l_cm33_rpmsg_linux_rtos_example_non_secure_vector.bin
fatload mmc 1:N 0x40010000 rzg2l_cm33_rpmsg_linux_rtos_example_non_secure_code.bin
cm33 start_debug 0x1001FF80 0x00010000
dcache on
```

Note: If N = 1, using "fatload". If N = 2, using "ext4load".

6. CM33 sample program is now started.

Note:

In Step 5, start_debug is a boot method that allows a debugger to connect to the Cortex-M33.

If you do not want to allow debugger connection, please replace start_debug with start_normal when executing.

Note that there is no difference in execution speed regardless of which command is used.

4.3.3 CM33 sample program invocation with remoteproc

Here is the procedure for invoking CM33 sample program with remoteproc:

1. Booting up Linux by following **5. Booting and Running Linux of SMARC EVK of RZ/G2L Linux Start-up Guide**.
2. Invoke the command stated below to specify the sample program to be loaded:

```
root@smarc-rzg2l:~# echo rzg2l_cm33_rpmsg_linux_rtos_example.elf >
/sys/class/remoteproc/remoteproc0/firmware
```

3. Kick CM33 by invoking the command below:

```
root@smarc-rzg2l:~# echo start > /sys/class/remoteproc/remoteproc0/state
```

If CM33 sample program starts to work successfully, the following message should be shown on Linux console:

```
root@smarc-rzg2l:~# echo start > /sys/class/remoteproc/remoteproc0/state
[ 737.289773] remoteprocremoteproc0: powering up cm33
[ 737.348226] remoteprocremoteproc0: Booting fwimage rzg2l_cm33_rpmsg_linux_rtos_example.elf, size
1347660
[ 737.366255] remoteproc0#vdev0buffer: assigned reserved memory node vdev0buffer@0x43200000
[ 737.374784] remoteproc0#vdev0buffer: registered virtio0 (type 7)
[ 737.380989] remoteprocremoteproc0: remote processor cm33 is now up
```

Note: The firmware components are stored in the file system at **/lib/firmware** folder. Please replace it if any updates to firmware.

4.4 CA55 sample program invocation

This section describes how to invoke CA55 sample program.

1. Boot up Linux by executing the following command on u-boot:

```
=> run bootcmd
```

2. Login as **root**.

```
smarc-rzg2l login: root
```

3. Run CA55 sample program by executing the following command:

```
root@smarc-rzg2l:~# rpmsg_sample_client
```

4. Then, you can see the following message on the console relative to CN14 of SMARC carrier board. Be sure that you invoke CM33 sample program in advance.

```
Successfully probed IPI device
metal: info:      metal_uio_dev_open: No IRQ for device 42f00000.rsctbl.
Successfully open uio device: 42f00000.rsctbl.
Successfully added memory device 42f00000.rsctbl.
metal: info:      metal_uio_dev_open: No IRQ for device 43000000.vring-ctl0.
Successfully open uio device: 43000000.vring-ctl0.
Successfully added memory device 43000000.vring-ctl0.
metal: info:      metal_uio_dev_open: No IRQ for device 43200000.vring-shm0.
Successfully open uio device: 43200000.vring-shm0.
Successfully added memory device 43200000.vring-shm0.
metal: info:      metal_uio_dev_open: No IRQ for device 43100000.vring-ctl1.
Successfully open uio device: 43100000.vring-ctl1.
Successfully added memory device 43100000.vring-ctl1.
metal: info:      metal_uio_dev_open: No IRQ for device 43500000.vring-shm1.
Successfully open uio device: 43500000.vring-shm1.
Successfully added memory device 43500000.vring-shm1.
metal: info:      metal_uio_dev_open: No IRQ for device 42f01000.mhu-shm.
Successfully open uio device: 42f01000.mhu-shm.
Successfully added memory device 42f01000.mhu-shm.
Initialize remoteproc successfully.
Initialize remoteproc successfully.
```

```
*****
*   rpmsg communication sample program   *
*****
```

1. communicate with RZ/G2L CM33 ch0
2. communicate with RZ/G2L CM33 ch1

```
e. exit
```

```
please input
>
```

5. Type 1 if RPMsg channel 0 is used on CM33 RPMsg sample program. Also, type 2 if RPMsg channel 1 is used on the sample program.

4.5 Overview of sample program behavior

The behavior of sample program is stated below:

1. Wait until a communication channel between CA55 and CM33 is established.
2. Once the communication channel is established, CA55 sample program starts to send the message to CM33 by incrementing its size from the minimum value 17 to the maximum value 488. When sending the message, the following log should be shown on Linux console:

```
Sending payload number 148 of size 165
```

3. When CM33 receives the message sent from CA55, the echo reply is sent back to CA55.
4. When CA55 receives the echo reply, the message below should be displayed in the console:

```
echo test: sent : 165
received payload number 148 of size 165
```

5. After the message which has 488 bytes sized payload is sent from CA55 to CM33 and CM33 sends back the echo reply, the message for terminating the communication channel is sent from CA55 to CM33. Then, CA55 and CM33 sample programs output the following log messages to the corresponding consoles respectively when receiving the termination message.

- **On CA55 side:**

```
*****
*   rpmsg communication sample program   *
*****
```

1. communicate with RZ/G2L CM33 ch0
2. communicate with RZ/G2L CM33 ch1

```
e. exit
```

```
please input
>
```

If you would like to quit the application, please type **e**.

- **On CM33 side:**

```
De-initializing remoteproc
```

6. Finally, CM33 sample program re-waits for the establishment of connection channel. You can see the following log on the console a short time later:

```
creating remoteproc virtio
initializing rpmsg vdev
```

5. Assignment of peripherals

Table 5.1 shows the expected assignment of peripherals to sub core (CM33) on this example project while all other devices remain assigned to the Linux (main core) side.

Table 5.1 Peripherals assignment on RZ/G2L Multi-OS Example Project

Peripherals	CPU		Remarks
	Main core CA55	Sub core CM33	
GTM	ch0-1	ch2	0002-arm64-dts-renesas-rzg2l-smarc-Disable-OSTM2.patch 0005-arm64-dts-renesas-rzg2lc-smarc-Disable-SCIF1-OSTM2.patch 0007-arm64-dts-renesas-rzg2ul-smarc-Disable-OSTM2.patch
SCIF	ch0, ch2-4	G2L: ch2 G2LC: ch1	0005-arm64-dts-renesas-rzg2lc-smarc-Disable-SCIF1-OSTM2.patch 0006-clk-renesas-r9a07g044-Set-SCIF1-SCIF2-OSTM2.patch

6. Appendix

6.1 Setting for RPMsg Example supporting OpenAMP v2024.05

For support OpenAMP v2024.05, the RPMsg examples require additional preprocessor to build and run successfully with the updated virtio/OpenAMP configuration as below:

`VIRTIO_DRIVER_SUPPORT=1` for the Master core .
`VIRTIO_DEVICE_SUPPORT=1` for the Slave core .

Configuration path:

e² studio (GCC): *Properties* → *Cross ARM C Compiler* → *Preprocessor* → *Defined symbols*

7. Reference Documents

- R01AN5924: RZ/G2L, RZ/G2LC, RZ/G2UL, RZ/G3S and RZ/G3E Getting Started with Flexible Software Package
- R01US0616: RZ/G2L, RZ/G2LC and RZ/G2UL-EVKIT Linux Start-up Guide
- R01UH0964: RZ/G2L, RZ/V2L SMARC Module Board User's Manual
- R01UH0966: RZ SMARC Series Carrier Board User's Manual

Revision History

Rev.	Date	Description	
		Page	Summary
3.00	Jul.22.2025	-	First edition
3.10	Dec.26.2025	-	Updated to align with RZ MPU Verified Linux Package v4.0.1.
3.20	Feb.06.2026	-	Update Multi-OS package version to 3.2.0.
4.00	Mar.31.2026	-	Update Multi-OS package version to 4.0.0.
4.10	Jun.30.2026	-	Update Multi-OS package version to 4.1.0.
4.20	Sep.03.2026	-	Update Multi-OS package version to 4.2.0.

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Precaution against Electrostatic Discharge (ESD)

A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity.

Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.

2. Processing at power-on

The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.

3. Input of signal during power-off state

Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.

4. Handling of unused pins

Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.

5. Clock signals

After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.

6. Voltage application waveform at input pin

Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (Max.) and V_{IH} (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (Max.) and V_{IH} (Min.).

7. Prohibition of access to reserved addresses

Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.

8. Differences between products

Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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